

11-17-1999

Docket No. 0107-113



101202020

MUD 11/3/99

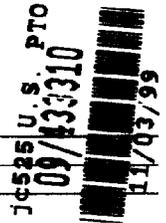
To the Honorable Commissioner of Patent and Trademarks. Please record the attached original documents or copy thereof.

1 Name of conveying party(ies): Minoru NUMOTO

Additional name(s) of conveying party(ies) attached?  Yes  No

2 Name and address of receiving party(ies):

Name: Tokyo Seimitsu Co., Ltd.  
Street Address: 7-1, Shimorenjaku 9-chome  
City Mitaka-shi, Tokyo Country Japan ZIP \_\_\_\_\_



Additional name(s) & addresses(es) attached?  Yes  No

3. Name of Conveyance:

- Assignment  Merger
- Security Agreement  Change of Name
- Other \_\_\_\_\_

Execution Date: October 27, 1999

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: October 27, 1999  
Title WAFER POLISHING APPARATUS

A: Patent Application No.

B. Patent No.(s)

Additional numbers attached?  Yes  No

09/433310

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David S. Safran  
Street Address: 8180 Greensboro Drive, Suite 800  
City: McLean State: Virginia ZIP 22102

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): .....\$ 40.00

- Enclosed
- Authorized to be charged to deposit account, for any deficiency in fee.

8. Deposit Account Number: 19-2380  
(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

David S. Safran  
Name of Person Signing

Signature

November 3, 1999  
Date

Total number of pages including cover sheet, attachments, and document: 3

11/15/1999 SDW/S  
02 FC:581

ATTORNEY DOCKET NO.

# ASSIGNMENT

Serial No. \_\_\_\_\_

Filed \_\_\_\_\_

WHEREAS, Minoru NUMOTO

Insert Name(s)  
of Inventor(s)

Insert Title of  
Invention

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in \_\_\_\_\_

WAFER POLISHING APPARATUS

Insert Date of  
Signing of  
Application

for which an application for Letters Patent of the United States of America has been executed by the undersigned on \_\_\_\_\_; and

Insert Name of  
Assignee

WHEREAS, \_\_\_\_\_

Tokyo Seimitsu Co., Ltd.

Insert Address  
of Assignee

of 7-1, Shimorenjaku 9-chome, Mitaka-shi, Tokyo, Japan

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America and its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or any continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims under or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Sixbey, Friedman, Leedom & Ferguson, P.C. the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

In witness whereof, this Assignment has been executed by the undersigned on the date(s) opposite the undersigned name(s).

Date Oct. 27, 1999, Name of Inventor MINORU NUMOTO (SEAL)  
 Minoru NUMOTO (signature)

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_ (SEAL)  
 (signature)

(This assignment should preferably be acknowledged before a United States Consul or Notary Public. If not, then the execution by the Inventor(s) should be witnessed by at least two other persons who should sign here.)

Witness Kenzo Matsuura [Signature]  
 (name) (signature)

Witness Fumio Haraguchi [Signature]  
 (name) (signature)

Witness Fumihiko Nomura [Signature]  
 (name) (signature)